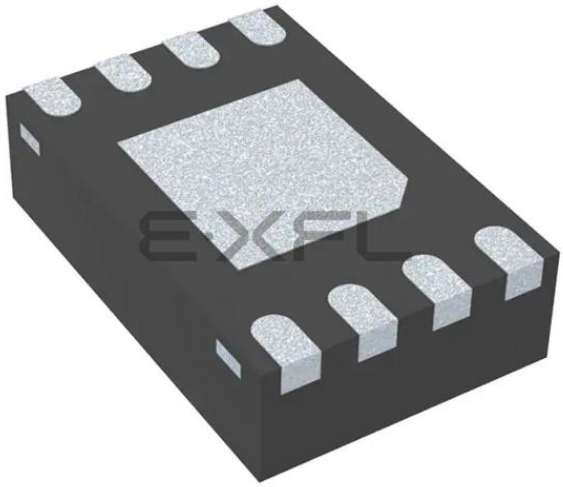

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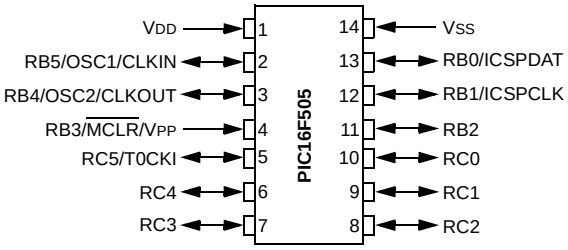
Applications of "Embedded - Microcontrollers"

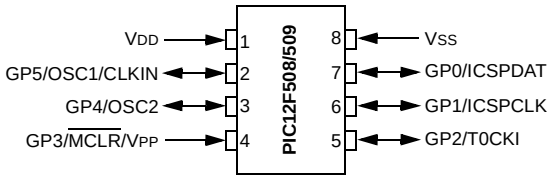
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	768B (512 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VFDFN Exposed Pad
Supplier Device Package	8-DFN (2x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f508-e-mc

Pin Diagrams

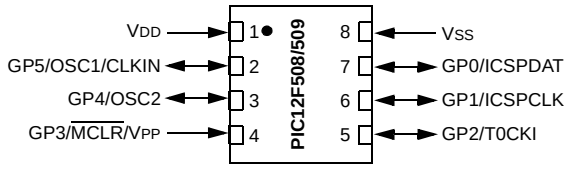
PDIP, SOIC, TSSOP



PDIP, SOIC, MSOP



DFN



PIC16F505 16-Pin Diagram (QFN)

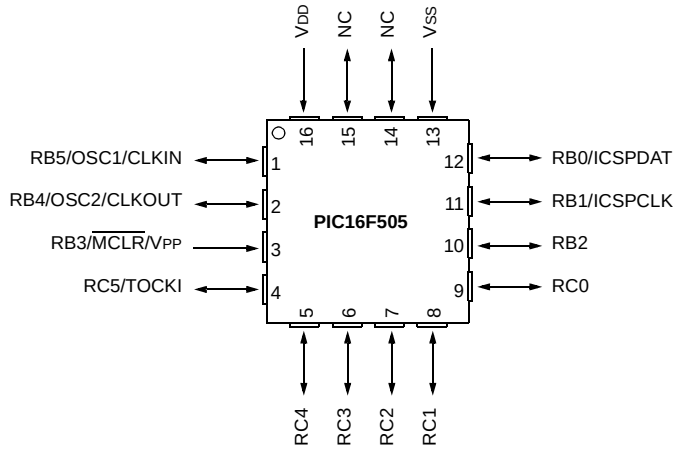
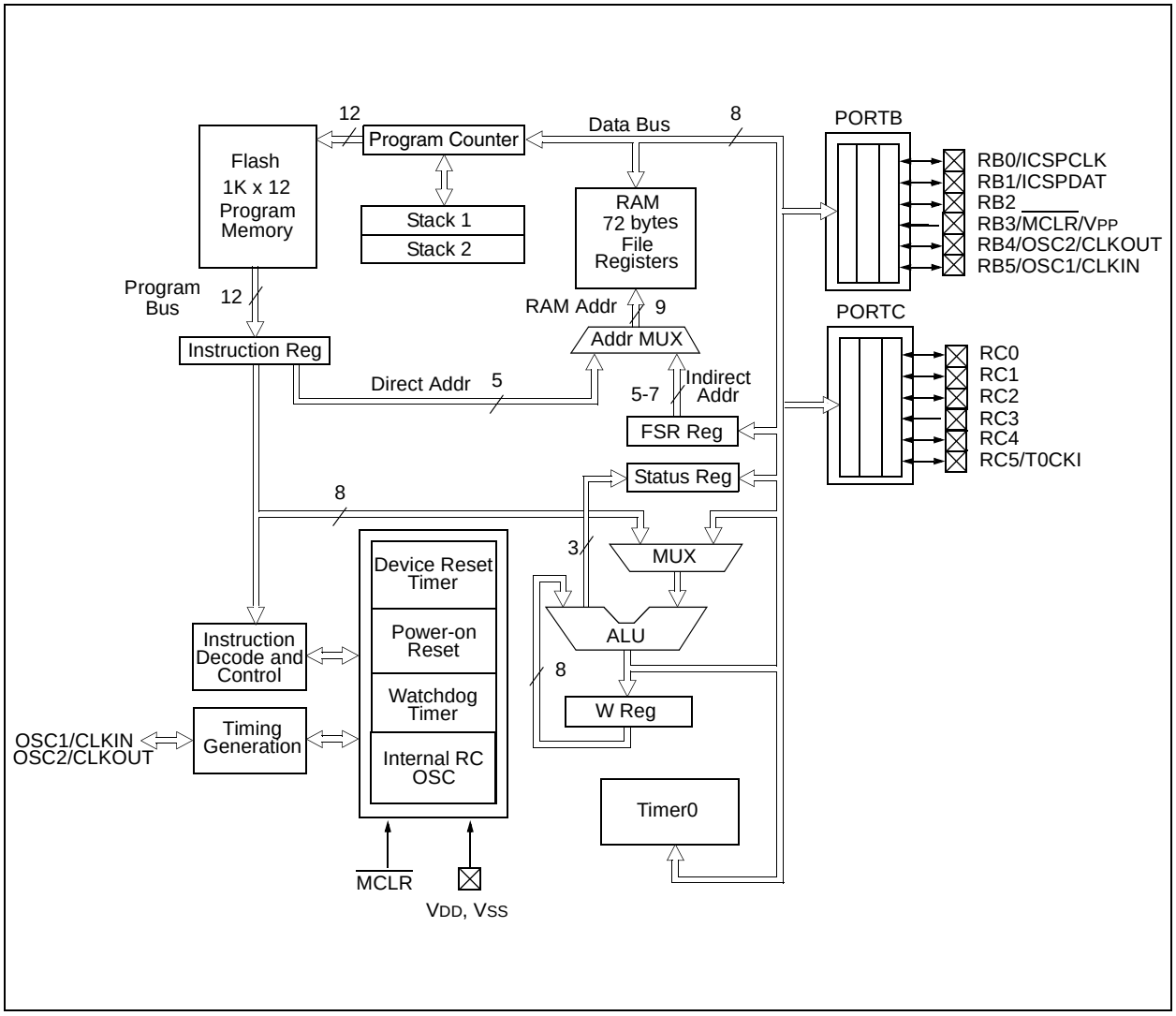


FIGURE 3-2: PIC16F505 BLOCK DIAGRAM



3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the PC is incremented every Q1 and the instruction is fetched from program memory and latched into the instruction register in Q4. It is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-3 and Example 3-1.

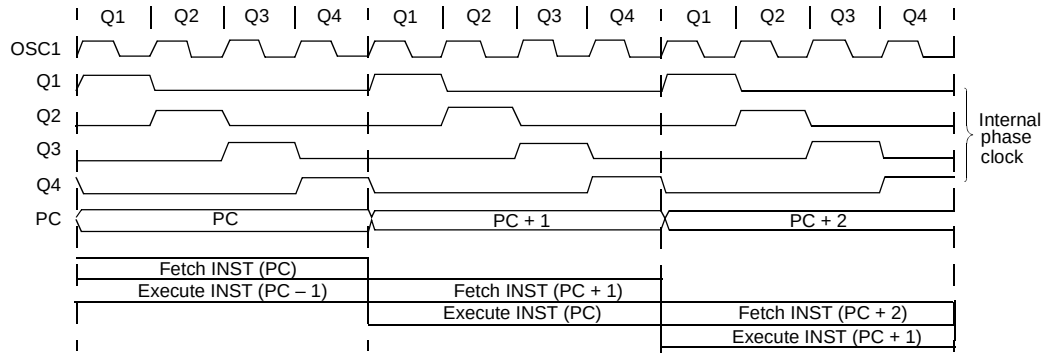
3.2 Instruction Flow/Pipelining

An instruction cycle consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle, while decode and execute take another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the PC to change (e.g., `GOTO`), then two cycles are required to complete the instruction (Example 3-1).

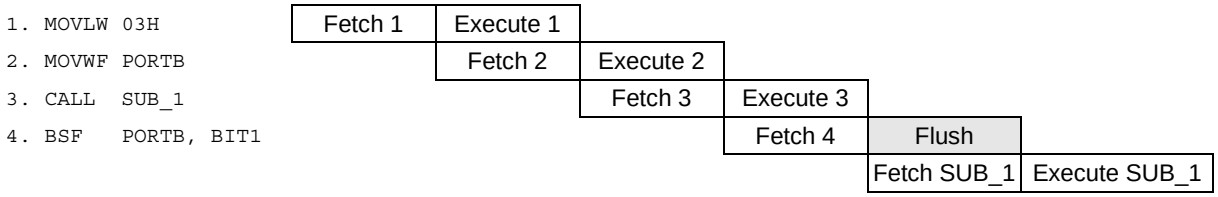
A fetch cycle begins with the PC incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-3: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



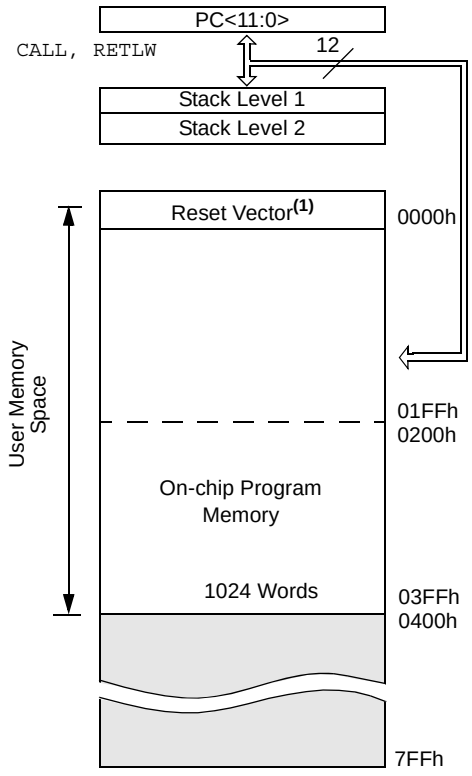
All instructions are single cycle, except for any program branches. These take two cycles, since the fetch instruction is “flushed” from the pipeline, while the new instruction is being fetched and then executed.

4.2 Program Memory Organization For The PIC16F505

The PIC16F505 device has a 11-bit Program Counter (PC) capable of addressing a 2K x 12 program memory space.

The 1K x 12 (0000h-03FFh) for the PIC16F505 are physically implemented. Refer to Figure 4-2. Accessing a location above this boundary will cause a wrap-around within the first 1K x 12 space. The effective Reset vector is at 0000h (see Figure 4-2). Location 03FFh contains the internal oscillator calibration value. This value should never be overwritten.

FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F505



Note 1: Address 0000h becomes the effective Reset vector. Location 03FFh contains the `MOVLW XX` internal oscillator calibration value.

4.3 Data Memory Organization

Data memory is composed of registers or bytes of RAM. Therefore, data memory for a device is specified by its register file. The register file is divided into two functional groups: Special Function Registers (SFR) and General Purpose Registers (GPR).

The Special Function Registers include the TMR0 register, the Program Counter (PCL), the STATUS register, the I/O registers (ports) and the File Select Register (FSR). In addition, Special Function Registers are used to control the I/O port configuration and prescaler options.

The General Purpose Registers are used for data and control information under command of the instructions.

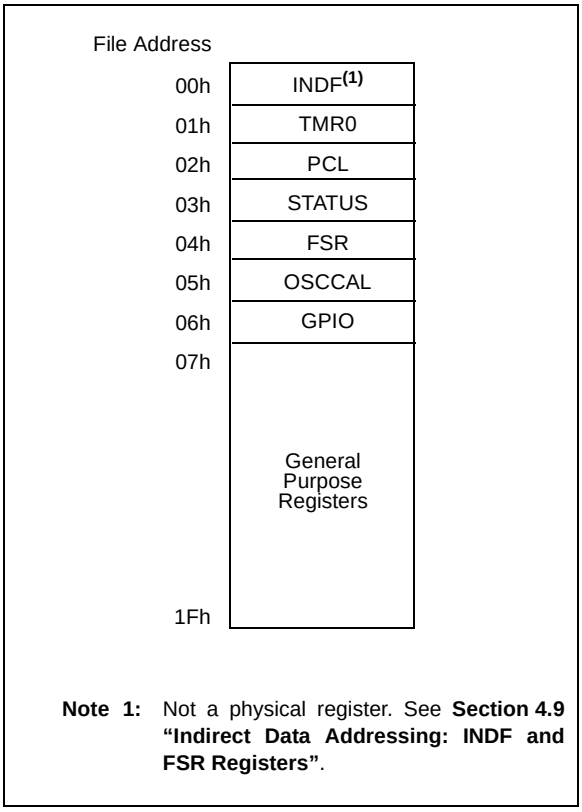
For the PIC12F508/509, the register file is composed of 7 Special Function Registers, 9 General Purpose Registers and 16 or 32 General Purpose Registers accessed by banking (see Figure 4-3 and Figure 4-4).

For the PIC16F505, the register file is composed of 8 Special Function Registers, 8 General Purpose Registers and 64 General Purpose Registers accessed by banking (Figure 4-5).

4.3.1 GENERAL PURPOSE REGISTER FILE

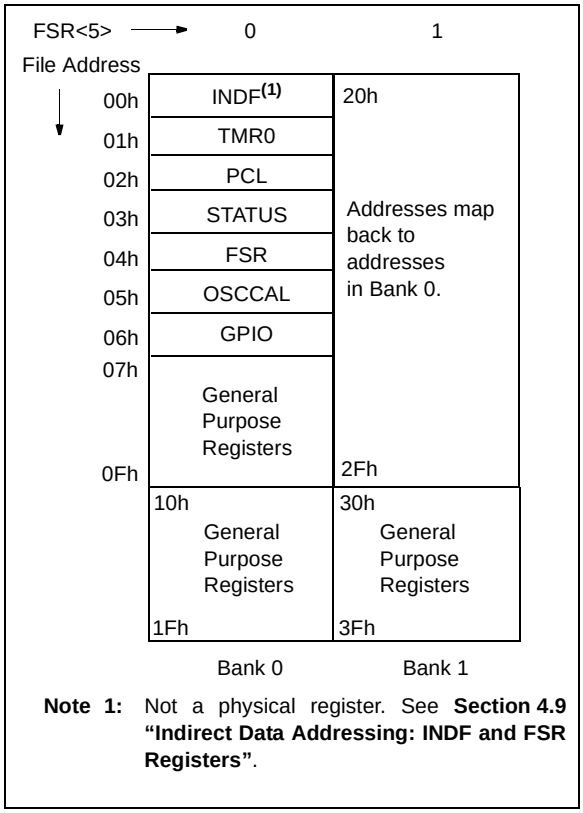
The General Purpose Register file is accessed, either directly or indirectly, through the File Select Register (FSR). See **Section 4.9 “Indirect Data Addressing: INDF and FSR Registers”**.

FIGURE 4-3: PIC12F508 REGISTER FILE MAP



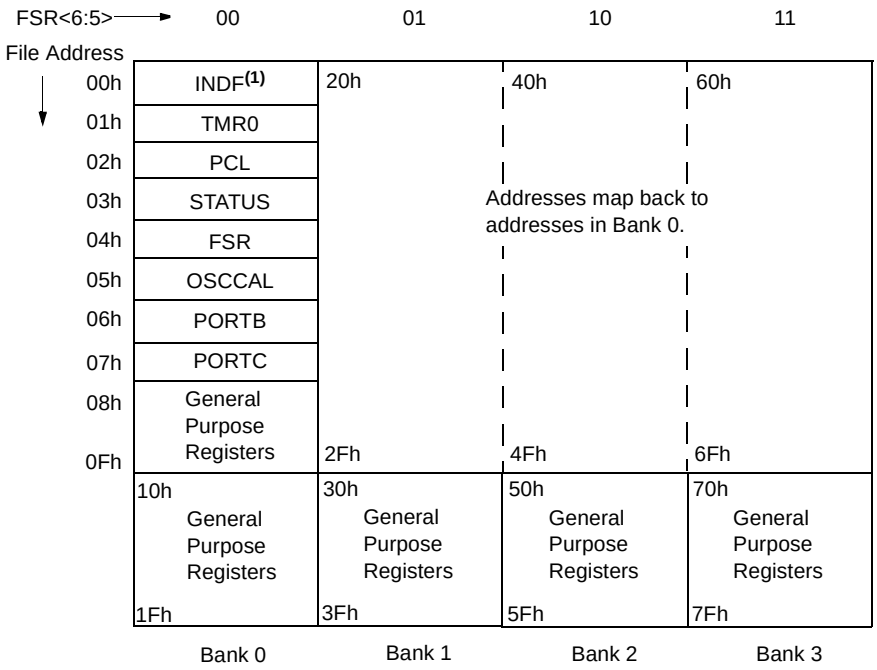
Note 1: Not a physical register. See **Section 4.9 "Indirect Data Addressing: INDF and FSR Registers"**.

FIGURE 4-4: PIC12F509 REGISTER FILE MAP



Note 1: Not a physical register. See **Section 4.9 "Indirect Data Addressing: INDF and FSR Registers"**.

FIGURE 4-5: PIC16F505 REGISTER FILE MAP



Note 1: Not a physical register. See **Section 4.9 "Indirect Data Addressing: INDF and FSR Registers"**.

REGISTER 4-2: STATUS REGISTER (ADDRESS: 03h) (PIC16F505)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
RBWUF	—	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **RBWUF:** PORTB Reset bit
1 = Reset due to wake-up from Sleep on pin change
0 = After power-up or other Reset

bit 6 **Reserved**: Do not use

bit 5 **PA0**: Program Page Preselect bits
1 = Page 1 (200h-3FFh)
0 = Page 0 (000h-1FFh)
Each page is 512 bytes.
Using the PA0 bit as a general purpose read/write bit in devices which do not use it for program page preselect is not recommended, since this may affect upward compatibility with future products.

bit 4 **$\overline{TO}$**: Time-Out bit
1 = After power-up, CLRWDT instruction, or SLEEP instruction
0 = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-Down bit
1 = After power-up or by the CLRWDT instruction
0 = By execution of the SLEEP instruction

bit 2 **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit Carry/$\overline{Borrow}$ bit (for ADDWF and SUBWF instructions)
ADDWF:
1 = A carry from the 4th low-order bit of the result occurred
0 = A carry from the 4th low-order bit of the result did not occur
SUBWF:
1 = A borrow from the 4th low-order bit of the result did not occur
0 = A borrow from the 4th low-order bit of the result occurred

bit 0 **C**: Carry/$\overline{Borrow}$ bit (for ADDWF, SUBWF and RRF, RLF instructions)

ADDWF:	SUBWF:	RRF or RLF:
1 = A carry occurred	1 = A borrow did not occur	Load bit with LSb or MSb, respectively
0 = A carry did not occur	0 = A borrow occurred	

REGISTER 7-2: CONFIGURATION WORD FOR PIC16F505(1)

—	—	—	—	—	—	MCLRE	$\overline{CP}$	WDTE	FOSC2	FOSC1	FOSC0
bit 11											bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 11-6 **Unimplemented**: Read as '0'

bit 5 **MCLRE:** RB3/$\overline{MCLR}$ Pin Function Select bit
1 = RB3/$\overline{MCLR}$ pin function is $\overline{MCLR}$
0 = RB3/$\overline{MCLR}$ pin function is digital input, $\overline{MCLR}$ internally tied to V_{DD}

bit 4 **$\overline{CP}$:** Code Protection bit
1 = Code protection off
0 = Code protection on

bit 3 **WDTE:** Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 2-0 **FOSC<1:0>:** Oscillator Selection bits
111 = External RC oscillator/CLKOUT function on RB4/OSC2/CLKOUT pin
110 = External RC oscillator/RB4 function on RB4/OSC2/CLKOUT pin
101 = Internal RC oscillator/CLKOUT function on RB4/OSC2/CLKOUT pin
100 = Internal RC oscillator/RB4 function on RB4/OSC2/CLKOUT pin
011 = EC oscillator/RB4 function on RB4/OSC2/CLKOUT pin
010 = HS oscillator
001 = XT oscillator
000 = LP oscillator

Note 1: Refer to the "*PIC16F505 Memory Programming Specifications*" (DS41226) to determine how to access the Configuration Word. The Configuration Word is not user addressable during device operation.

7.2 Oscillator Configurations

7.2.1 OSCILLATOR TYPES

The PIC12F508/509/16F505 devices can be operated in up to six different oscillator modes. The user can program up to three Configuration bits (FOSC<1:0> [PIC12F508/509], FOSC<2:0> [PIC16F505]). To select one of these modes:

- LP: Low-Power Crystal
- XT: Crystal/Resonator
- HS: High-Speed Crystal/Resonator (PIC16F505 only)
- INTRC: Internal 4 MHz Oscillator
- EXTRC: External Resistor/Capacitor
- EC: External High-Speed Clock Input (PIC16F505 only)

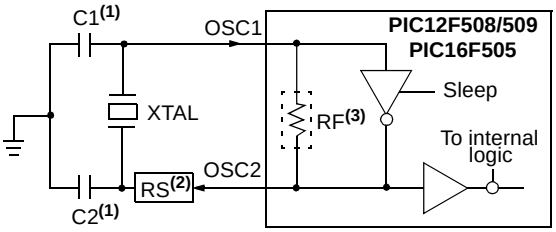
7.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In HS (PIC16F505), XT or LP modes, a crystal or ceramic resonator is connected to the (GP5/RB5)/OSC1/(CLKIN) and (GP4/RB4)/OSC2/(CLKOUT) pins to establish oscillation (Figure 7-1). The PIC12F508/509/16F505 oscillator designs require the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in HS (PIC16F505), XT or LP modes, the device can have an external clock source drive the (GP5/RB5)/OSC1/CLKIN pin (Figure 7-2). When the part is used in this fashion, the output drive levels on the OSC2 pin are very weak. This pin should be left open and unloaded. Also, when using this mode, the external clock should observe the frequency limits for the clock mode chosen (HS, XT or LP).

Note 1: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.

2: The user should verify that the device oscillator starts and performs as expected. Adjusting the loading capacitor values and/or the Oscillator mode may be required.

FIGURE 7-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF approx. value = 10 MΩ.

FIGURE 7-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

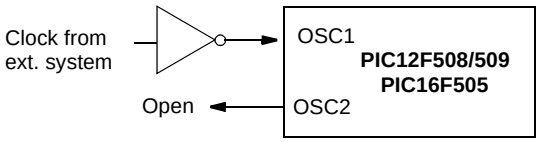


TABLE 7-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS – PIC12F508/509/16F505(1)

Osc Type	Resonator Freq.	Cap. Range C1	Cap. Range C2
XT	4.0 MHz	30 pF	30 pF
HS(2)	16 MHz	10-47 pF	10-47 pF

Note 1: These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

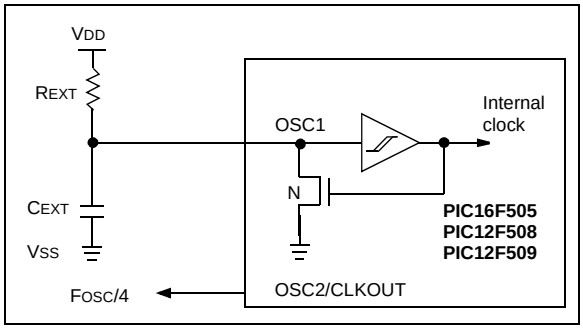
2: PIC16F505 only.

Although the oscillator will operate with no external capacitor (C_{EXT} = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

Section 10.0 "Electrical Characteristics" shows RC frequency variation from part-to-part due to normal process variation. The variation is larger for larger values of R (since leakage current variation will affect RC frequency more for large R) and for smaller values of C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications section for variation of oscillator frequency due to V_{DD} for given R_{EXT}/C_{EXT} values, as well as frequency variation due to operating temperature for given R, C and V_{DD} values.

FIGURE 7-5: EXTERNAL RC OSCILLATOR MODE



7.2.5 INTERNAL 4 MHz RC OSCILLATOR

The internal RC oscillator provides a fixed 4 MHz (nominal) system clock at V_{DD} = 5V and 25°C, (see **Section 10.0 "Electrical Characteristics"** for information on variation over voltage and temperature).

In addition, a calibration instruction is programmed into the last address of memory, which contains the calibration value for the internal RC oscillator. This location is always uncode protected, regardless of the code-protect settings. This value is programmed as a `MOVLW XX` instruction where `XX` is the calibration value, and is placed at the Reset vector. This will load the W register with the calibration value upon Reset and the PC will then roll over to the users program at address 0x000. The user then has the option of writing the value to the OSCCAL Register (05h) or ignoring it.

OSCCAL, when written to with the calibration value, will "trim" the internal oscillator to remove process variation from the oscillator frequency.

Note:	Erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be read prior to erasing the part so it can be reprogrammed correctly later.

For the PIC12F508/509/16F505 devices, only bits <7:1> of OSCCAL are implemented. Bits CAL6-CAL0 are used for calibration. Adjusting CAL6-CAL0 from '`0000000`' to '`1111111`' changes the clock speed. See Register 4-5 for more information.

Note:	The `0` bit of OSCCAL is unimplemented and should be written as '`0`' when modifying OSCCAL for compatibility with future devices.

FIGURE 7-7: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

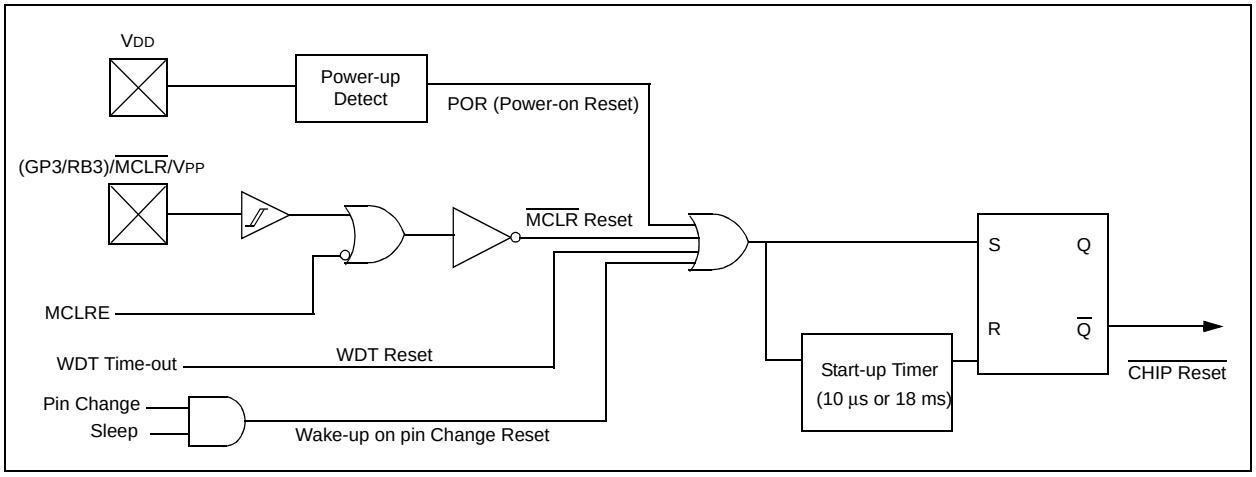


FIGURE 7-8: TIME-OUT SEQUENCE ON POWER-UP (MCLR PULLED LOW)

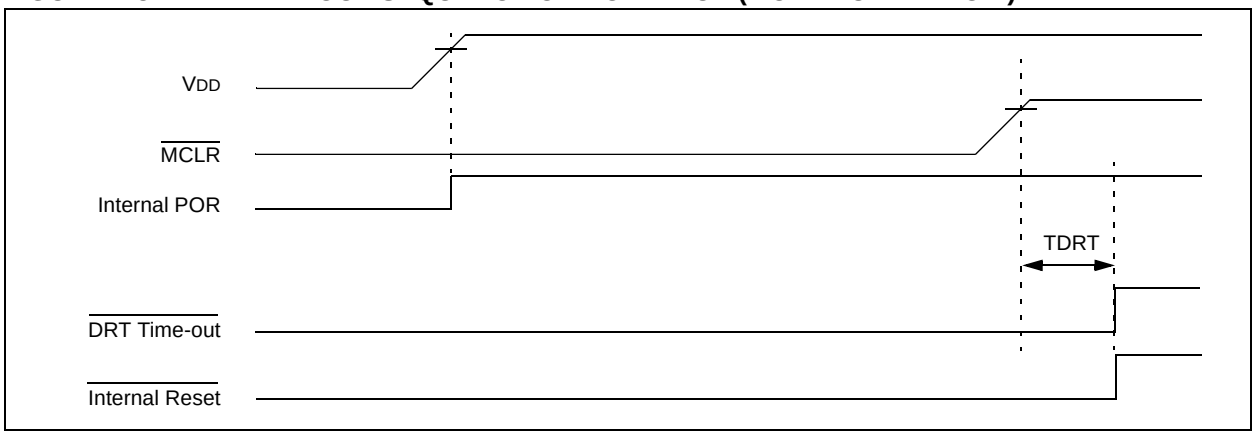


FIGURE 7-9: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): FAST VDD RISE TIME

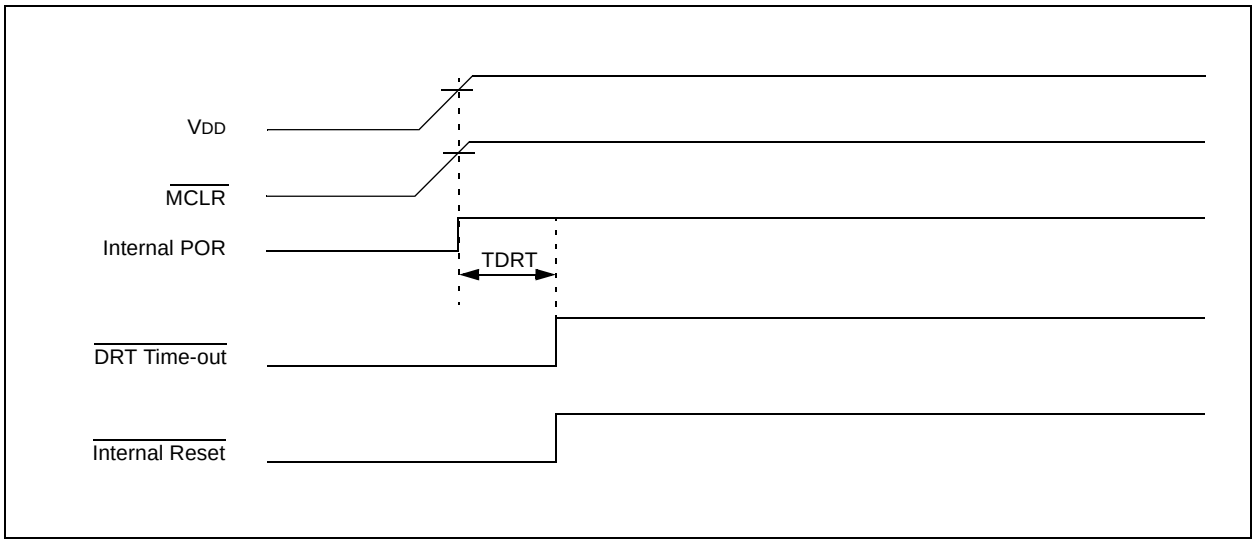
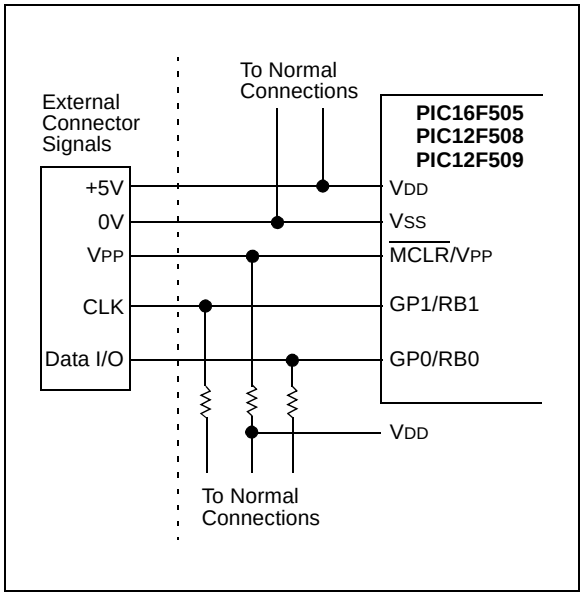


FIGURE 7-15: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



TRIS	Load TRIS Register
Syntax:	[*label*] TRIS f
Operands:	f = 6
Operation:	(W) → TRIS register f
Status Affected:	None
Description:	TRIS register 'f' (f = 6 or 7) is loaded with the contents of the W register

XORLW	Exclusive OR literal with W
Syntax:	[*label*] XORLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	0 ≤ f ≤ 31 d ∈ [0,1]
Operation:	(W) .XOR. (f) → (dest)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

9.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

9.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 and PIC24 families of microcontrollers and the dsPIC30 and dsPIC33 family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

9.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

9.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

9.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

TABLE 10-1: DC CHARACTERISTICS: PIC12F508/509/16F505 (Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating temperature -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended) Operating voltage VDD range as described in DC specification				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports:					
D030		with TTL buffer	Vss	—	0.8V	V	For all 4.5 ≤ VDD ≤ 5.5V
D030A			Vss	—	0.15 VDD	V	Otherwise
D031		with Schmitt Trigger buffer	Vss	—	0.15 VDD	V	
D032		$\overline{MCLR}$, T0CKI	Vss	—	0.15 VDD	V	
D033		OSC1 (in EXTRC)	Vss	—	0.15 VDD	V	**(Note1)**
D033		OSC1 (in HS)	Vss	—	0.3 VDD	V	**(Note1)**
D033		OSC1 (in XT and LP)	Vss	—	0.3	V	**(Note1)**
	VIH	**Input High Voltage**					
		I/O ports:		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	VDD	V	Otherwise
D041		with Schmitt Trigger buffer	0.85 VDD	—	VDD	V	For entire VDD range
D042		MCLR, T0CKI	0.85 VDD	—	VDD	V	
D043		OSC1 (in EXTRC)	0.85 VDD	—	VDD	V	**(Note1)**
D043		OSC1 (in HS)	0.7 VDD	—	VDD	V	**(Note1)**
D043		OSC1 (in XT and LP)	1.6	—	VDD	V	
D070	IPUR	**GPIO/PORTB weak pull-up current(4)**	50	250	400	µA	VDD = 5V, VPIN = VSS
	IIL	**Input Leakage Current(2), (3)**					
D060		I/O ports	—	—	± 1	µA	Vss ≤ VPIN ≤ VDD, Pin at high-impedance
D061		GP3/RB3/$\overline{MCLR}$I(5)	—	± 0.7	± 5	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	—	± 5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP oscillator configuration
		Output Low Voltage					
D080		I/O ports/CLKOUT	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D080A			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083		OSC2	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A			—	—	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C
		Output High Voltage					
D090		I/O ports/CLKOUT(3)	VDD – 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A			VDD – 0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092		OSC2	VDD – 0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D092A			VDD – 0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
		Capacitive Loading Specs on Output Pins					
D100		OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101		All I/O pins and OSC2	—	—	50	pF	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12F508/509/16F505 be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: The specification applies to all weak pull-up devices, including the weak pull-up on GP3/$\overline{MCLR}$. The current listed will be the same whether GP3/$\overline{MCLR}$ is configured as GP3 with a weak pull-up or enabled as $\overline{MCLR}$.

5: This specification applies when GP3/RB3/$\overline{MCLR}$ is configured as an input with pull-up disabled. The leakage current of the $\overline{MCLR}$ circuit is higher than the standard I/O logic.

FIGURE 11-4: MAXIMUM IPD VS. VDD (SLEEP MODE, ALL PERIPHERALS DISABLED)

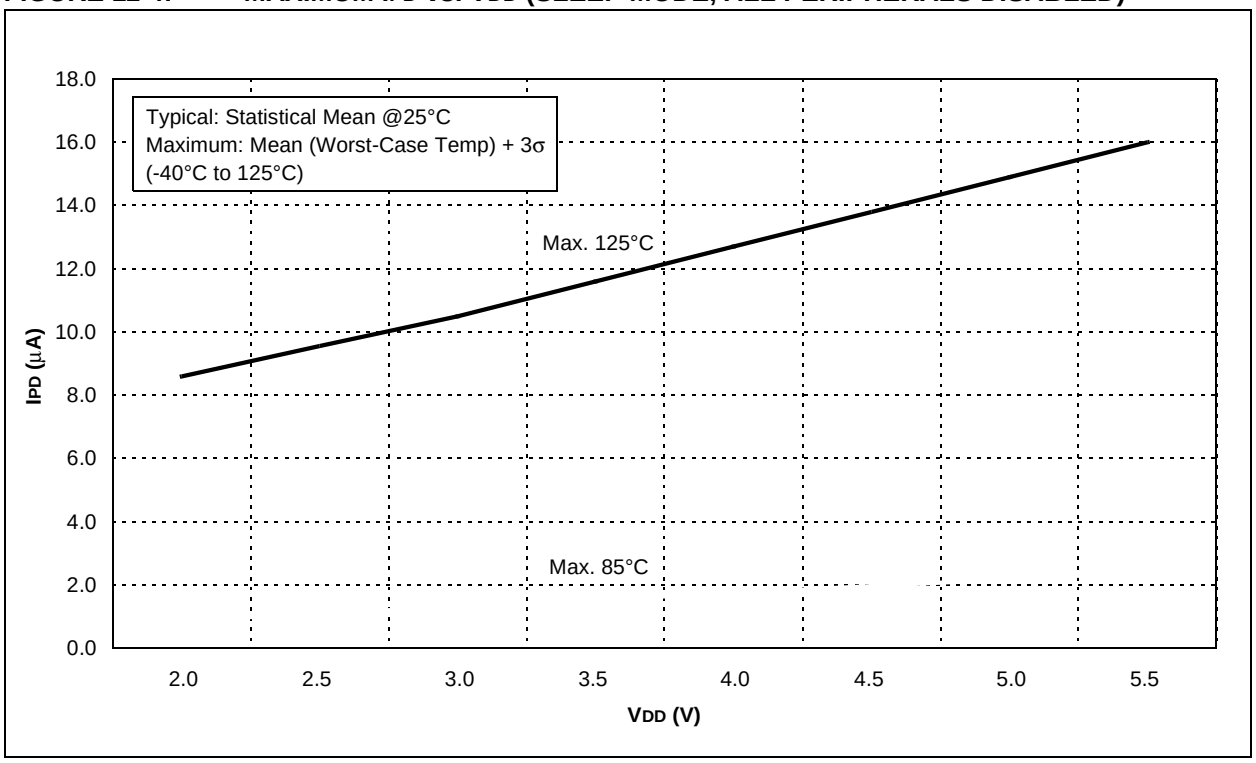


FIGURE 11-5: TYPICAL WDT IPD VS. VDD

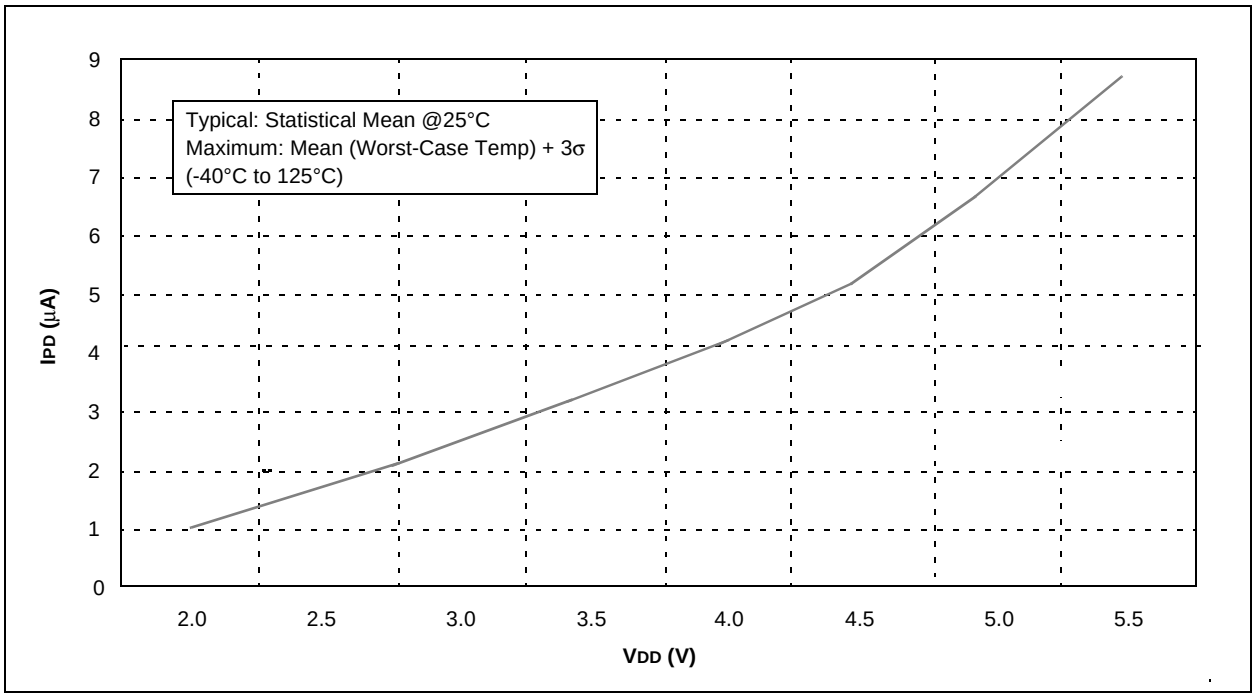


FIGURE 11-8: VOL vs. IOL OVER TEMPERATURE (VDD = 3.0V)

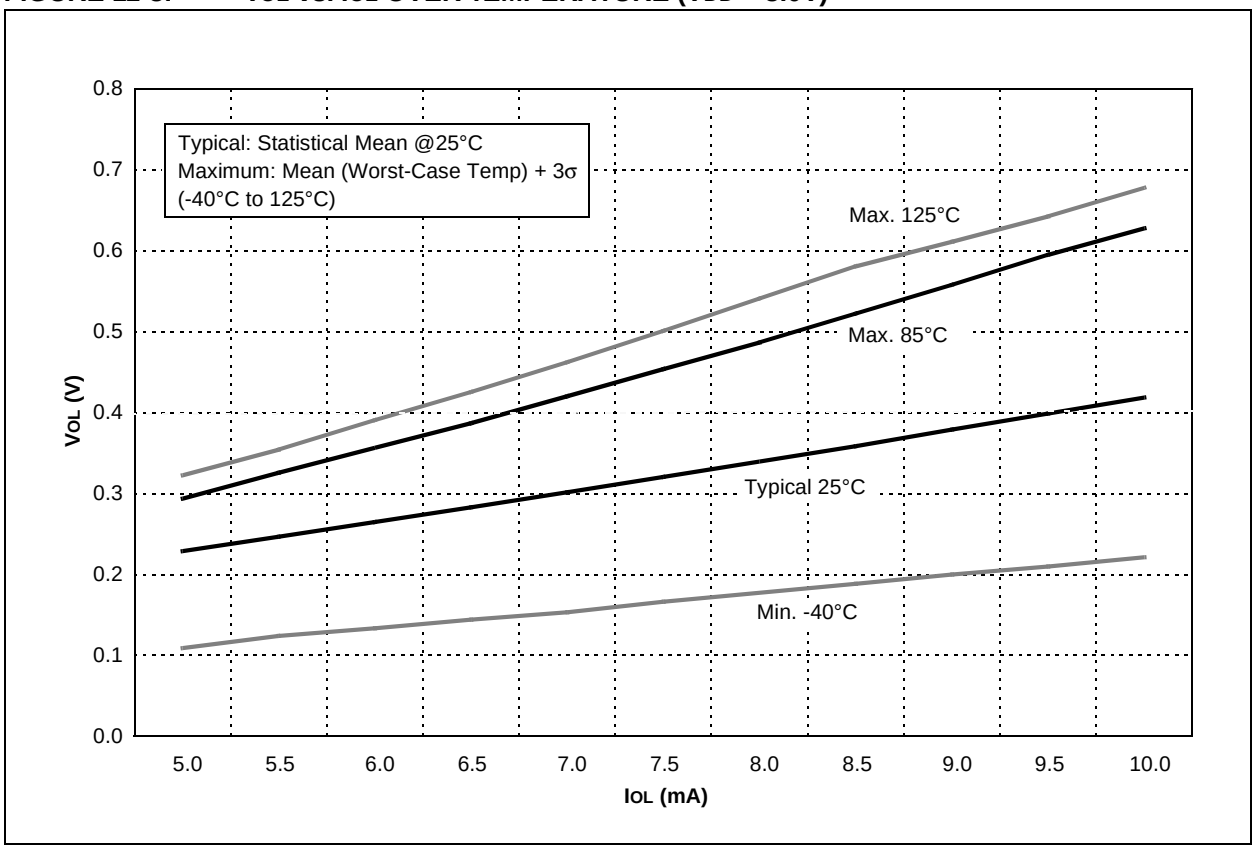
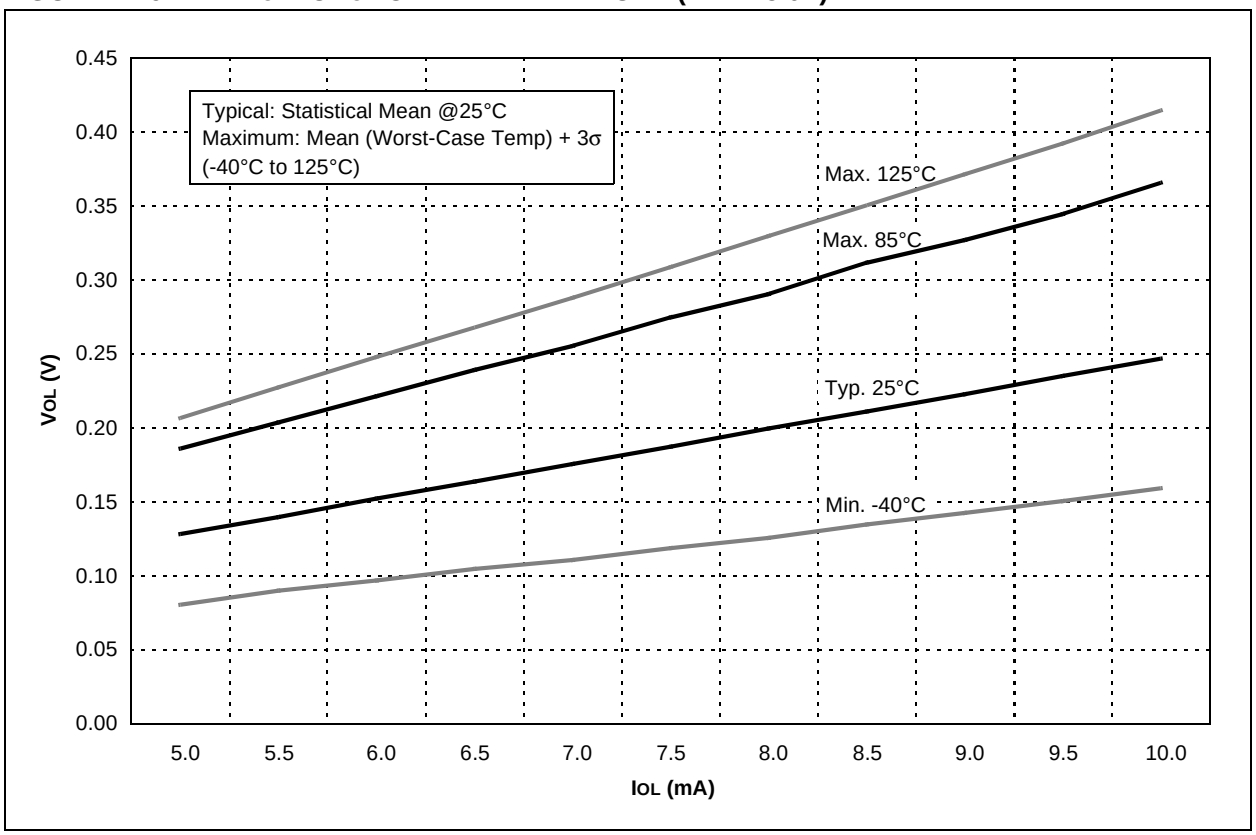


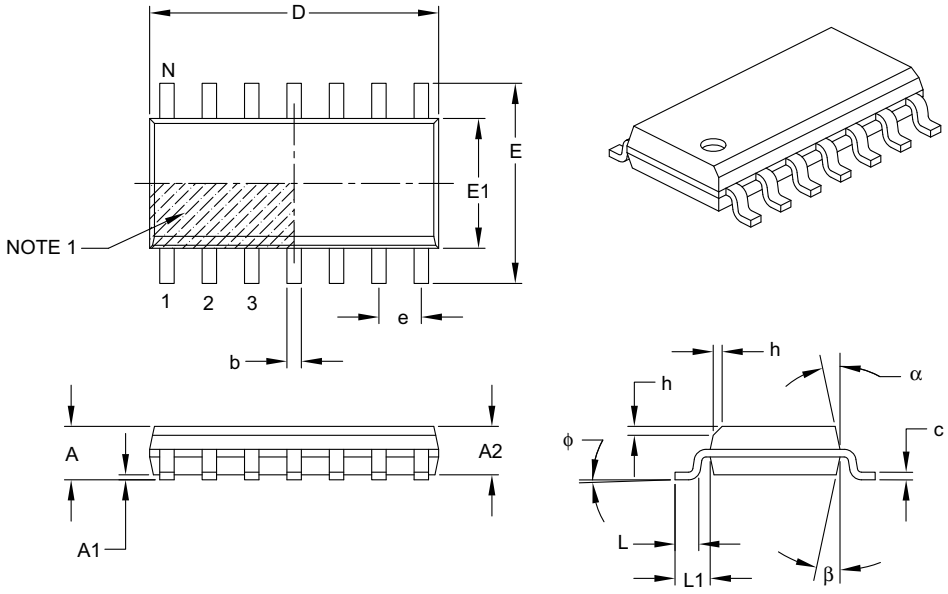
FIGURE 11-9: VOL vs. IOL OVER TEMPERATURE (VDD = 5.0V)



NOTES:

14-Lead Plastic Small Outline (SL) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	1.75
Molded Package Thickness	A2	1.25	–	–
Standoff §	A1	0.10	–	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (optional)	h	0.25	–	0.50
Foot Length	L	0.40	–	1.27
Footprint	L1		1.04 REF	
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.17	–	0.25
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

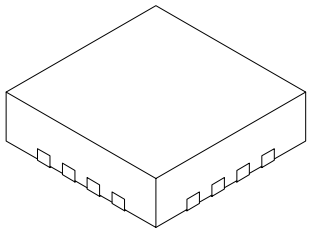
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-065B

16-Lead Plastic Quad Flat, No Lead Package (MG) - 3x3x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		3.00 BSC	
Exposed Pad Width	E2	1.00	1.10	1.50
Overall Length	D		3.00 BSC	
Exposed Pad Length	D2	1.00	1.10	1.50
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.25	0.35	0.45
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-142A Sheet 2 of 2

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